IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under bot international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mfg Information				
upplier	Information								,					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi										2024-04-24				
Contact Na	nme	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-E	nv-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
	Requester Item Number	Mfr Item	Number	umber Mfr Item Name			Effective Date Version Manufacturing Site		Anufacturing Site	W	eight*	UOM	Unit Type	
		FGB3040CS ES-1 Sense-Ign-I		ES-1 Sense-Ign-IGI	BT TO263	2024-04-24		C	CPA 1576.57		76.578	mg	Each	
	turing Proccess Inform												·	
	Terminal Plating / Grid Array I		Terminal Base	Alloy J-S	STD-020 MSL	Rating		ess Body To	Τ'	e Max Time at Peak	Temperatur	e Numb	er of Reflow Cyc	eles
]	Matte Tin (Sn) - annealed	(CU Alloy	1			260		C	30	seconds	3		
omments														
vel 1 - ma	ximum time at peak tempera	ture during sol	ldering is 10	30 seconds										
or more i	nformation regarding materi	al composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.0	mg	Supplier	Silicon (Si)	7440-21-3		6	mg
Die Attach Solder	9.157	mg	Supplier	Silver (Ag)	7440-22-4		0.2289	mg
			A	Lead (Pb)	7439-92-1	7a	8.4702	mg
			Supplier	Tin (Sn)	7440-31-5		0.4578	mg
Lead Frame	921.117	mg	Supplier	Silver (Ag)	7440-22-4		1.38	mg
			Supplier	Iron (Fe)	7439-89-6		0.553	mg
			Supplier	Copper (Cu)	7440-50-8		919.0003	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1837	mg
Mold Compound-Black	638.25	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		12.5	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		174.9998	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		12.5	mg
			Supplier	Carbon Black (C)	1333-86-4		1.25	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		437.0002	mg
Plating	0.224	mg	Supplier	Tin (Sn)	7440-31-5		0.224	mg
Wire Bond - Al	1.83	mg	Supplier	Aluminum (Al)	7429-90-5		1.83	mg